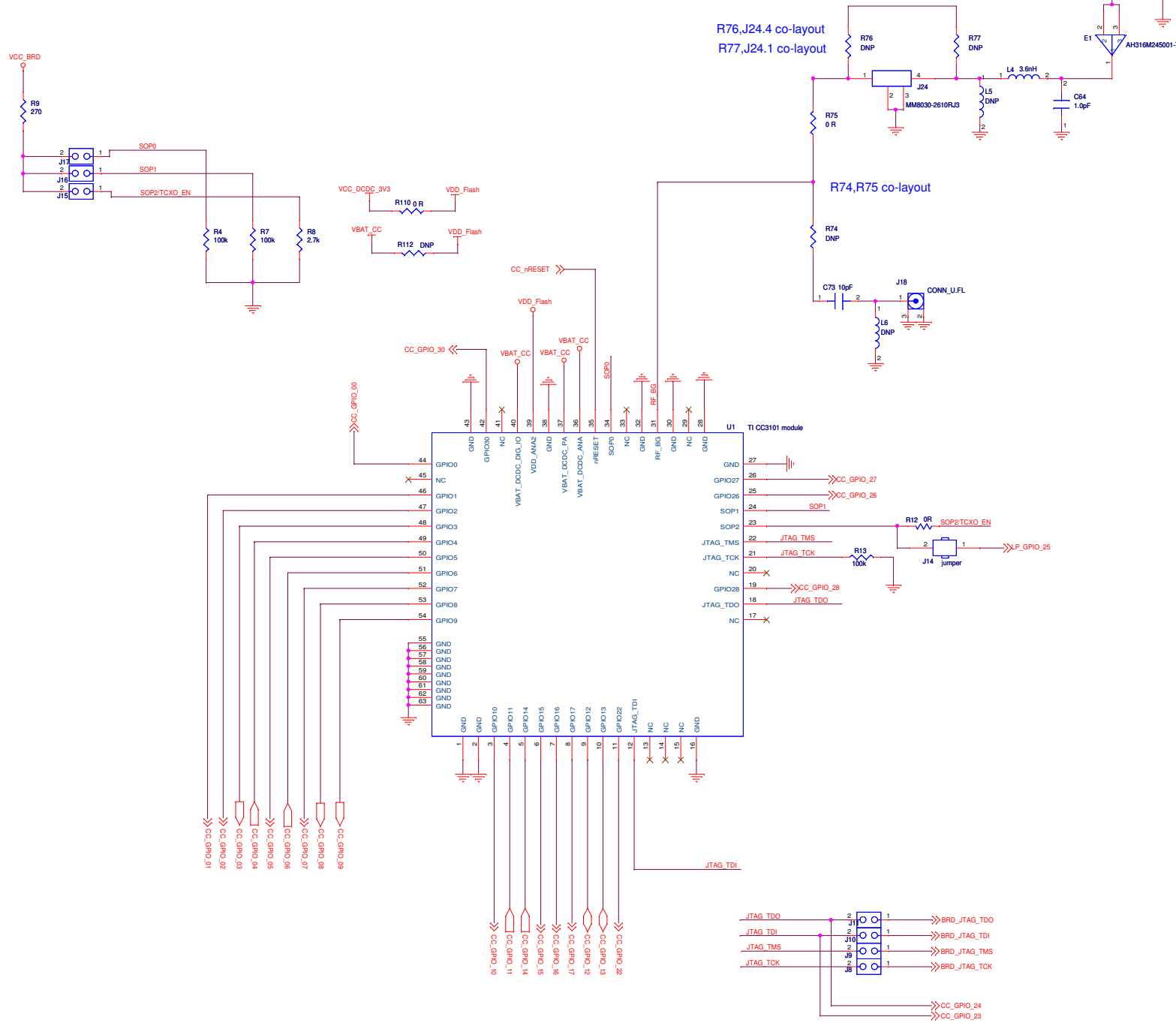
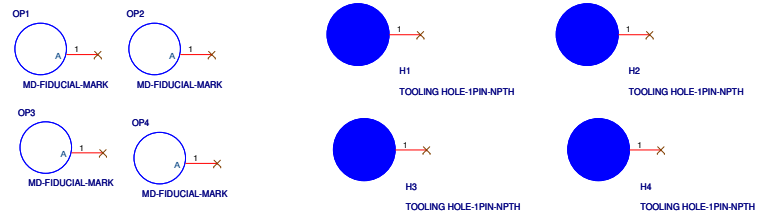
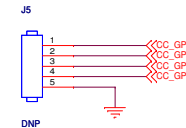
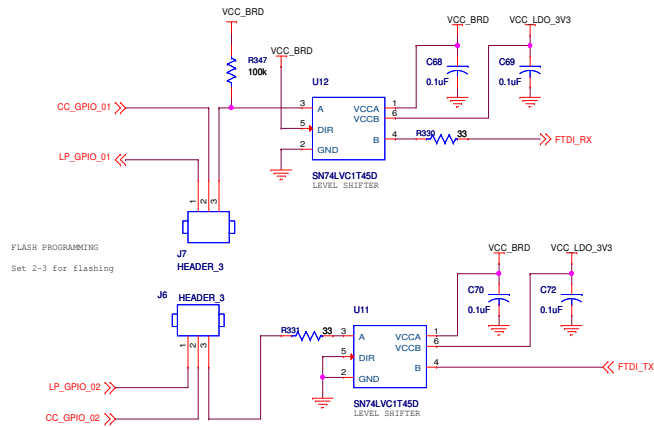
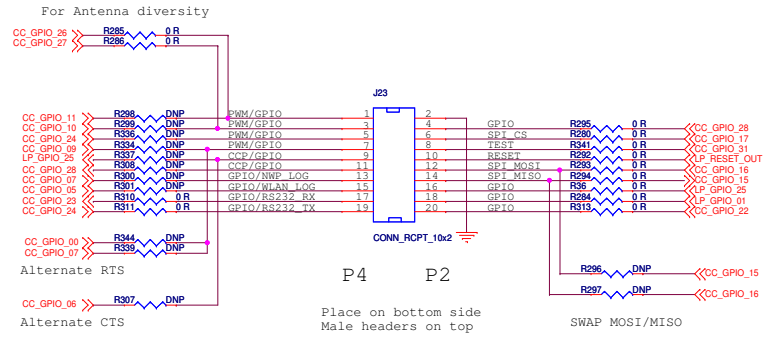
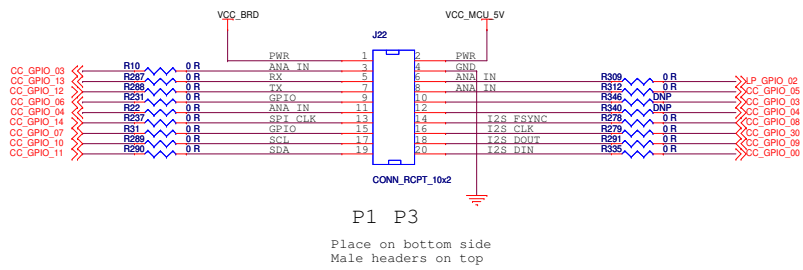


- V1.0 2013-11-13 Initia version.
- V1.1 2013-11-15 Change RF connector to U.FL
- V1.2 2013-12-15 Change antenna to Taiyo chip antenna
- V2.0 2014-03-06 Change to use FTDI IC
- V3.0 2014-03-12 Change as TI's requirement ---Foxconn_Mod_LP_Comments_V1.pdf
- V3.1 2014-03-18 Update the antenna matching circuit as per the LP 3.0B board.
- V3.2 2014-03-19 Update names of connectors, jumpers, LEDs as per the LP 3.0B board.
- V3.3 2014-03-26 Change R28 R343 size to 0402
- V3.4 2014-03-28 Change SW1, SW2, SW3 footprint to SW-1BT002S1
- V3.5 2014-04-11 Change J13 from 3pin to 2pin
- V3.6 2014-06-09 Change R8 from 10Kohm to 2.7Kohm
- V3.7 2014-07-16 Add 100k PD on P21 JTAG_TCK
- V3.8 2014-08-01 Change as TI's Comment "CC3200MODLP_Comments_V1.pdf"
- V3.9 2014-08-013 Change IC designators as TI reference board.

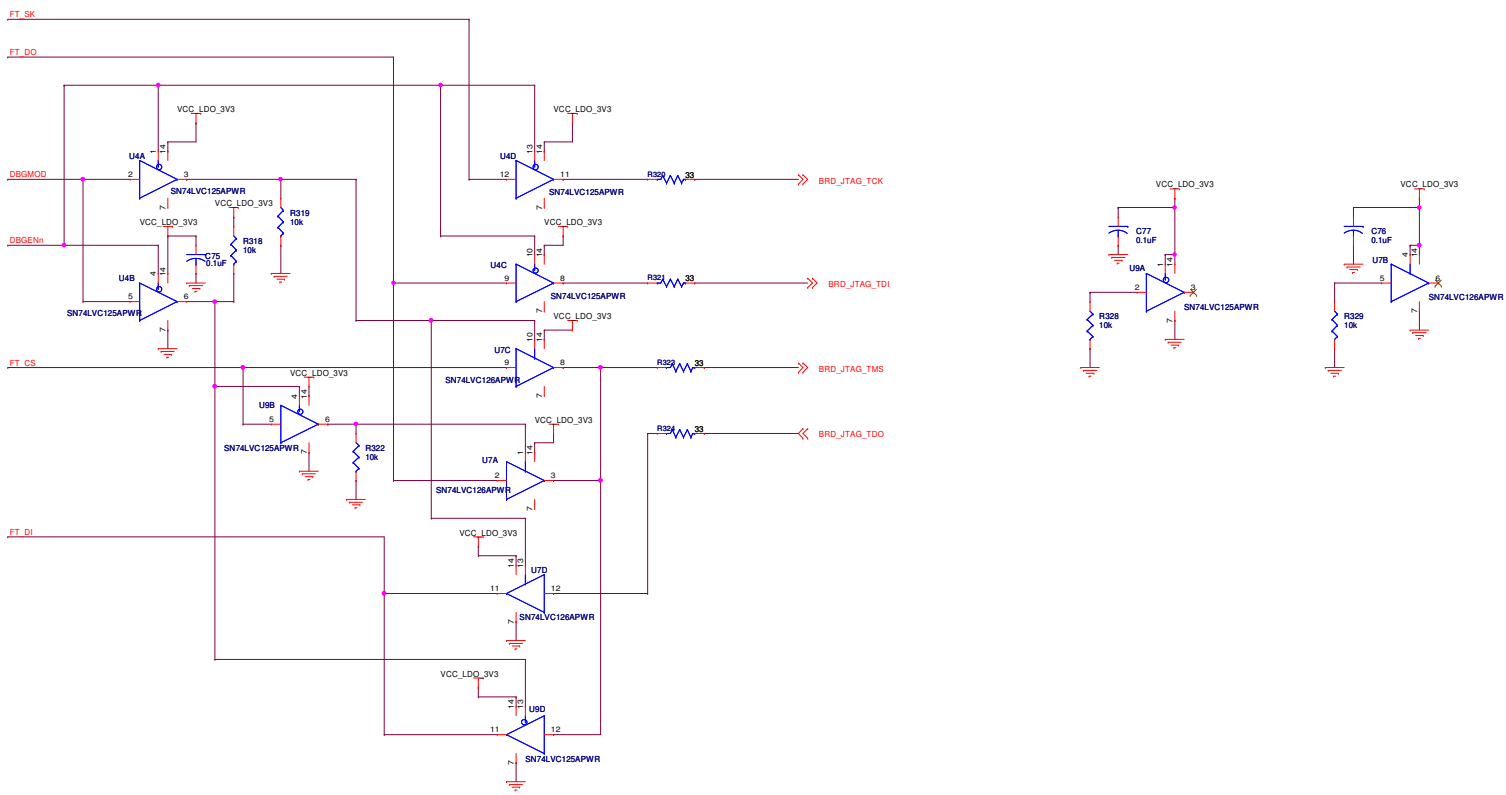
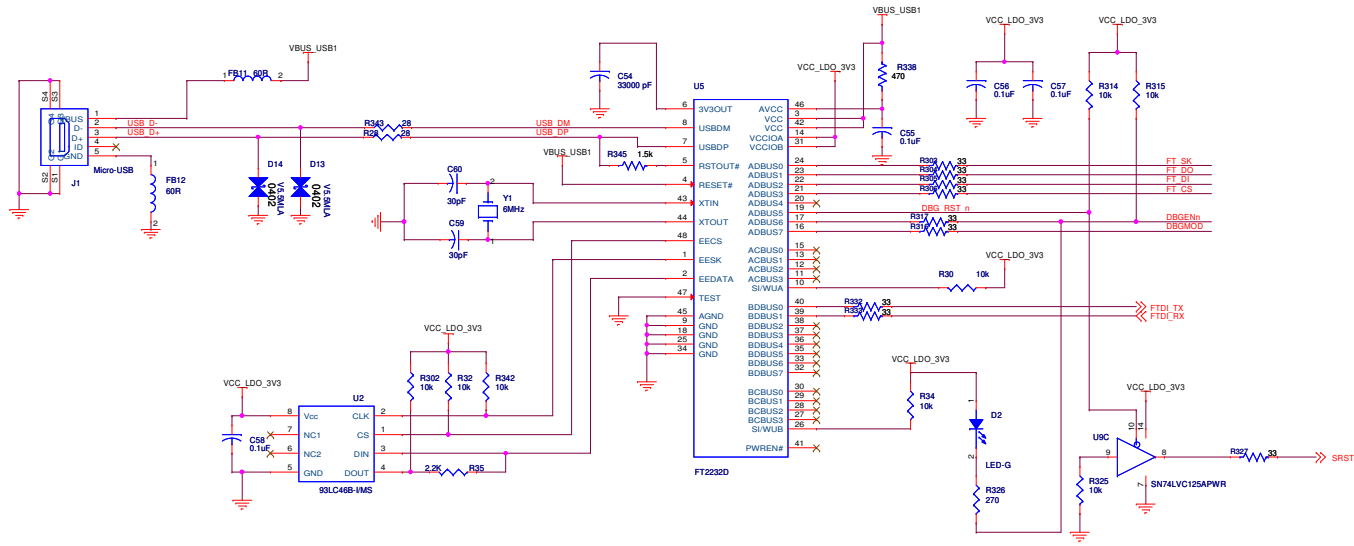
Title		
CC3101 EVB Launch Pad		
Size	Document Number	Rev
C	History Revision	3.9
Date:	Wednesday, August 20, 2014	Sheet 1 of 6



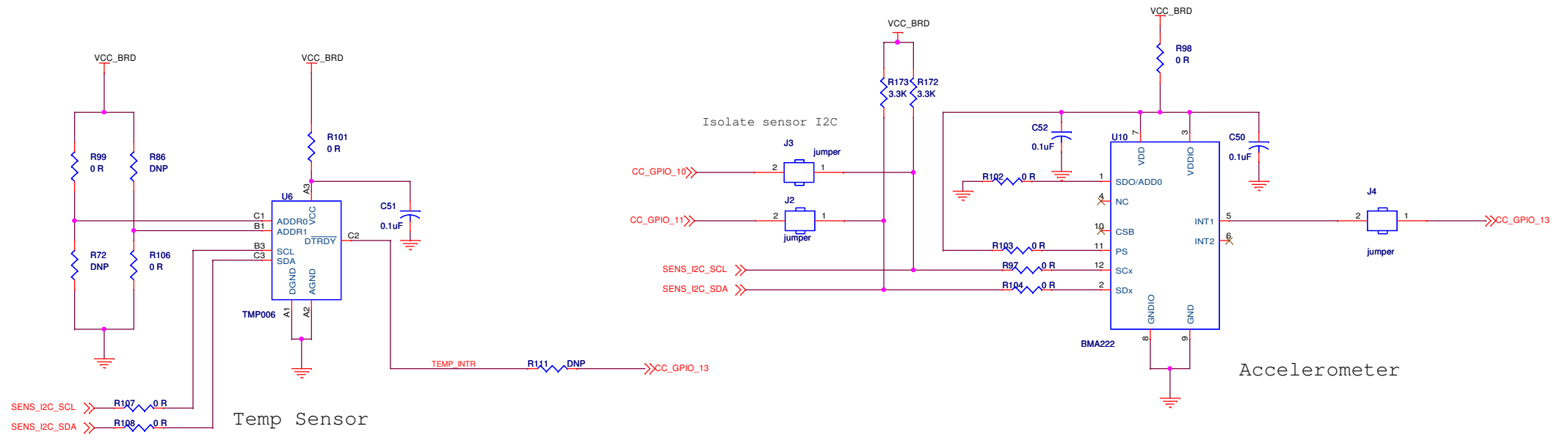
Title CC3101 EVB Launch Pad		
Size C	Document Number CC3101	Rev 3.9
Date Wednesday, August 20, 2014	Sheet 2 of 6	



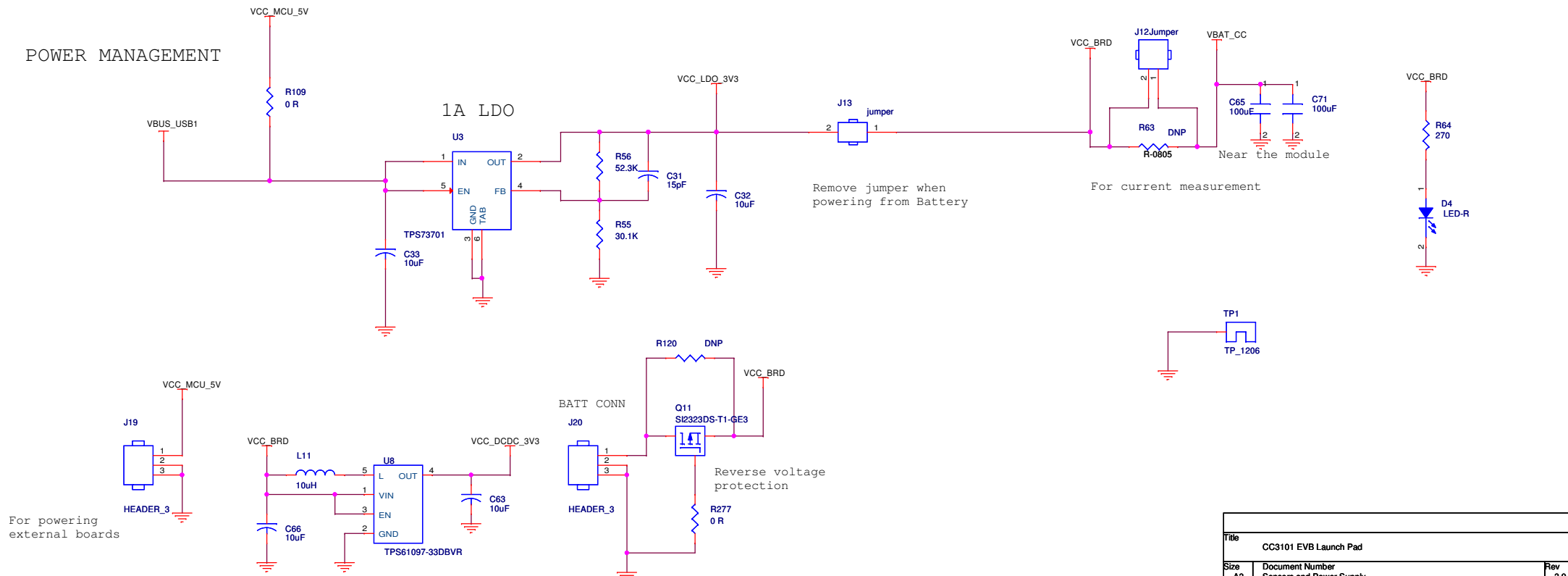
Title		
CC3101 EVB Launch Pad		
Size	Document Number	Rev
C	Host Interface	3.9
Date:	Wednesday, August 20, 2014	Sheet 3 of 6



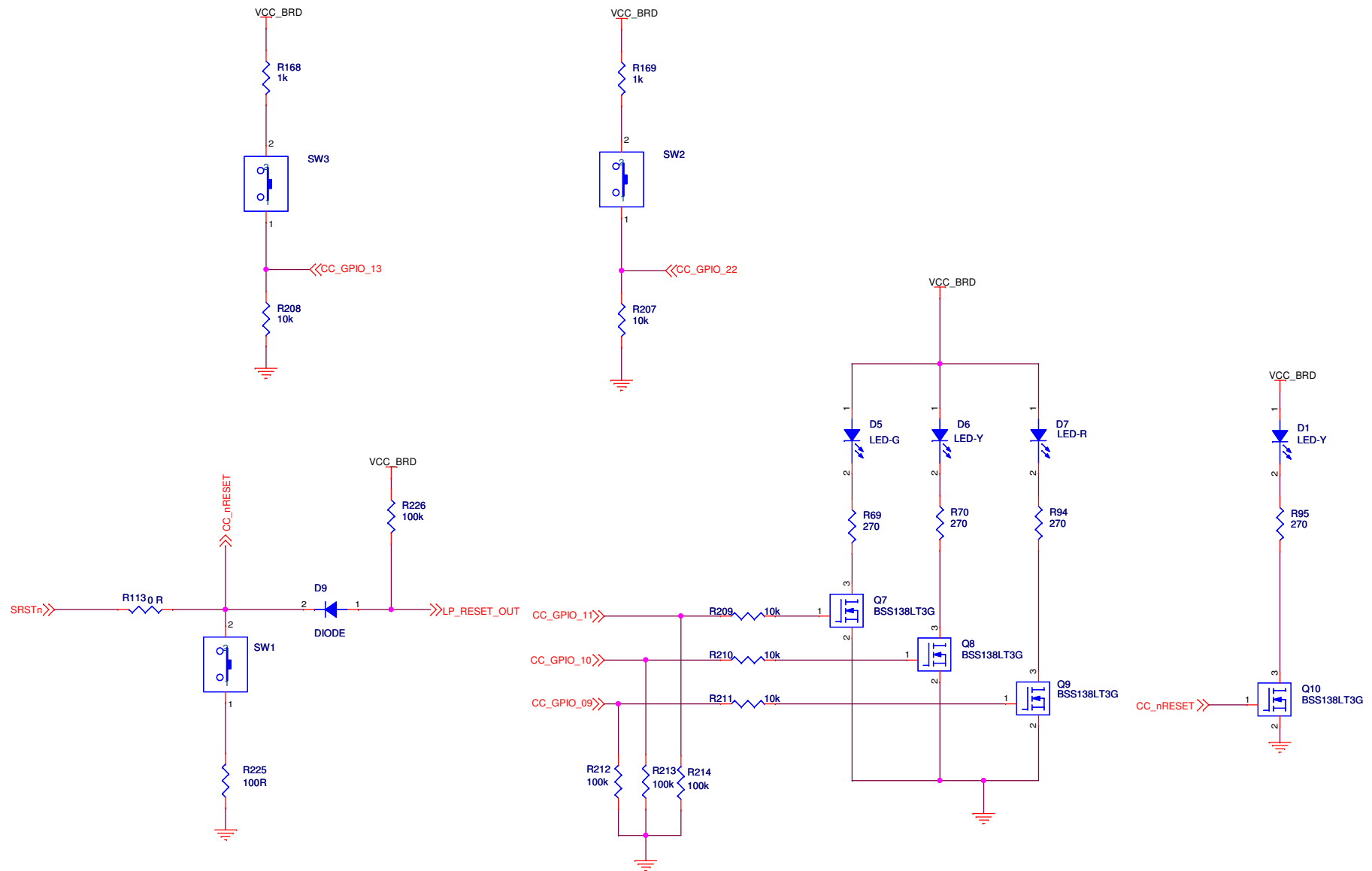
Title		
CC3101 EVB Launch Pad		
Size	Document Number	Rev
A2	FTDI	3.3
Date:	Wednesday, August 20, 2014	Sheet 4 of 5



POWER MANAGEMENT



Title		
CC3101 EVB Launch Pad		
Size	Document Number	Rev
A3	Sensors and Power Supply	3.9
Date:	Wednesday, August 20, 2014	Sheet 5 of 6



Title		
CC3101 EVB Launch Pad		
Size	Document Number	Rev
B	LEDs and Switches	3.9
Date:	Wednesday, August 20, 2014	Sheet 6 of 6

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